

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

Claims 1-19. (canceled).

Claim 20. (new): A wiring forming method comprising:

a first step of supplying a first liquid containing an insulating material on a substrate to form an insulated pattern on the substrate;

a second step of, after the first step, supplying a second liquid containing a conductive material on the substrate to form a first conductive pattern on the same layer that the first insulated pattern has been formed on;

a third step of, after the second step, applying the second liquid on the first conductive pattern to form a second conductive pattern on the first conductive pattern; and

a fourth step of, after the third step, applying the first liquid on the layer that the first insulated pattern and the first conductive pattern have been formed on to form a second insulated pattern on the same layer that the second conductive pattern has been formed on.

Claim 21. (new): The wiring forming method according to claim 20, wherein the first insulated pattern and the first conductive pattern are formed so that they come into contact with each other.

Claim 22. (new): The wiring forming method according to claim 20, wherein the first liquid and the second liquid are supplied by using an ink jet system.